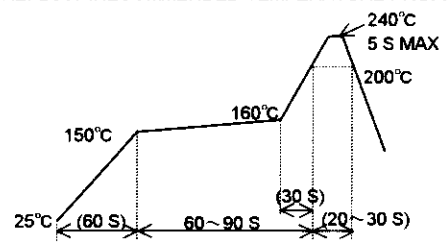


COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
△					△				
△					△				

APPLICATION STANDARD				
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C	STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C
	VOLTAGE	AC 50 V	OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY : 95 % MAX (NO DEW CONDENSATION IS PERMITTED)
	CURRENT	0.3 A		

SPECIFICATIONS						
ITEM	TEST METHOD	REQUIREMENT	QT	AT		
CONSTRUCTION						
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING	X	X		
MARKING	CONFIRMED VISUALLY.		X	X		
ELECTRICAL CHARACTERISTICS						
CONTACT RESISTANCE	100 mA (DC OR 1000 Hz).	70 mΩ MAX.	X	X		
INSULATION RESISTANCE	100 V DC.	100 MΩ MIN.	X	—		
VOLTAGE PROOF	150 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	X	X		
MECHANICAL CHARACTERISTICS						
INSERTION AND WITHDRAWAL FORCES	MEASURED BY APPLICABLE CONNECTOR.	INSERTION FORCE: 48 N MAX. WITHDRAWAL FORCE: 2 N MIN.	X	—		
MECHANICAL OPERATION	50 TIMES INSERTION AND EXTRACTIONS.	1) CONTACT RESISTANCE: 80 mΩ MAX. 2) NO DAMAGE, CRACK AND LOOSENESS OF PART.	X	—		
VIBRATION	FREQUENCY: 10 TO 55 Hz, SINGLE AMPLITUDE: 0.75 mm, — m/s ² AT 10 CYCLES FOR 3 DIRECTIONS.	1) NO ELECTRICAL DISCONTINUITY OF 1 μs MIN. 2) NO DAMAGE, CRACK AND LOOSENESS OF PART.	X	—		
SHOCK	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		X	—		
ENVIRONMENTAL CHARACTERISTICS						
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C. 90~95 %, 96 h.	1) CONTACT RESISTANCE: 80 mΩ MAX. 2) INSULATION RESISTANCE: 100 MΩ MIN.	X	—		
RAPID CHAGE OF TEMPERTURE	TEMPERTURE -55→15~35→ 85→15~35°C TIME 30→ 2~ 3→ 30→ 2~ 3 min. UNDER 5 CYCLES.	3) NO DAMAGE, CRACK AND LOOSENESS OF PART.	X	—		
DRY HEAT	EXPOSED AT 85 °C. 96 h.	1) CONTACT RESISTANCE: 80 mΩ MAX.	X	—		
COLD	EXPOSED AT -55 °C. 96 h.	2) NO DAMAGE, CRACK AND LOOSENESS OF PART.	X	—		
CORROSION SALT MIST	EXPOSED IN 5 % SALT WATER SPRAY FOR 48 h.	NO HEAVY CORROSION.	X	—		
SULPHUR DIOXIDE	EXPOSED IN 10 PPM FOR 96 h. (TEST STANDARD: JIS C 0090)	1) CONTACT RESISTANCE: 80 mΩ MAX. 2) NO HEAVY CORROSION.	X	—		
RESISTANCE TO SOLDERING HEAT	REFLOW : RECOMMENDED TEMPERATURE PROFILE  TO BE TESTED UNDER THE ABOVE CONDITIONS.	NO MELTING OF RESIN WHICH AFFECTS THE PERFORMANCE OF COMPONENT.	X	—		
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 235 °C FOR IMMERSION DURATION, 2 s.	NO PINHOLE OR DEWETTING ON SOLDERED SURFACE.	X	—		
REMARKS		DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
		<i>Mitsukawa</i>	<i>Mitsukawa</i>	<i>H. Okawa</i>	<i>T. Hashimura</i>	
UNLESS OTERWISE SPECIFIED ,REFER TO JIS C 5402.		00.06.20	00.06.20	00.06.21	00.06.23	
NOTE QT: QUALIFICATION TEST AT: ASSURANCE TEST X: APPLICABLE TEST						
HRS HIROSE ELECTRIC CO.,LTD.		SPECIFICATION SHEET		PART NO.		
				FX11B - 80S - SV (21)		
CODE NO.(OLD)	DRAWING NO.	CODE NO.				
CL	ELC4 - 152648 - 01	CL 573 - 0758 - 3 - 21	1 1			

FORM NO. 231-1

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TO
PCK